



AN10376

Mounting and soldering recommendations for CATV modules

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Application note

Document information

| Info | Content |
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| Abstract | Mounting recommendations for CATV hybrid modules |

Revision history

| Rev | Date | Description |
|-----|----------|--|
| 01 | 20050421 | Document format changed from DB1.5 to TDM format |
| 02 | 20051013 | Document updated and included soldering recommendations for Sn-plated leads products |

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1. Mounting Recommendations

The heatsink mounting surface must be flat, free of burrs and oxidation and parallel to the mounting surface.

The heatsink, mounting base and ground leads should be properly RF-grounded.

Heatsink compound should be applied sparingly and evenly on the mounting base.

When mounting CATV hybrid modules, the UNC screws must first be turned finger-tight. The screws should then be tightened to within the tolerance of 0.5 N-m minimum and 0.7 N-m maximum.

2. Soldering Recommendations

Leads may be plugged-in onto the corresponding sockets or soldered directly into the circuit for robustness and for better RF-connection. The latter is specifically recommended for products that use Sn-plated leads.

Soldering may be done using soldering iron with a maximum temperature of 260 °C for not more than 3 seconds when the soldered joints are a minimum of 3 mm from the module.

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